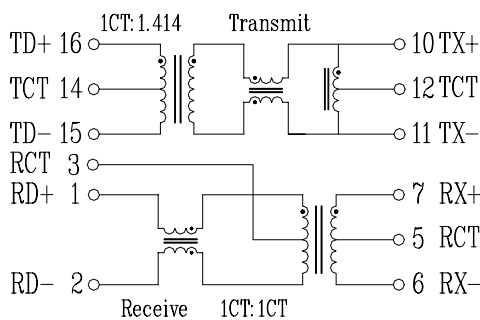


**P/N: 16ST1119 LF DATA SHEET****Feature**

- Meets all IEEE802.3 and ANSI X3.263 standards including 350uH OCL with 8mA Bias.
- Designed for use with transceivers from AMD , KENDIN Semiconductor , and Quality Semiconductor.
- IC grade transfer-molded package suitable for reflow soldering temperatures up to 235 .
- Patented interlock base construction for high reliability.
- Lead free for external pins.
- Operating temperature range:0 to +70 .
- Storage temperature range:-25 to +125 .

Electrical Specifications @ 25°C

Part Number	Turns Ratio (±5%)		Insertion Loss (dB Max)	Return Loss (dB Min)			Cross Talk (dB Min)		HI-POT (Vrms)
	RX	TX		30MHz	60MHz	80MHz	0.3-60MHz	60-100MHz	
16ST1119 LF	1CT:1CT	1CT:1.414	-2.0	-16	-11	-10	-45	-35	1500

Schematic**Mechanical**